Silicon N-Channel Dual Gate MOS FET

HITACHI

ADE-208-712A (Z) 2nd. Edition Dec. 1998

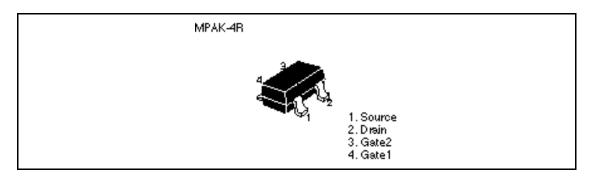
Application

UHF / VHF RF amplifier

Features

- Low noise figure.
 - NF = 1.0 dB typ. at f = 200 MHz
- Capable of low voltage operation
- Provide mini mold packages; MPAK-4R(SOT-143 var.)

Outline





Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DS}	12	V
Gate 1 to source voltage	V_{G1S}	±8	V
Gate 2 to source voltage	V _{G2S}	±8	V
Drain current	I _D	25	mA
Channel power dissipation	Pch	150	mW
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

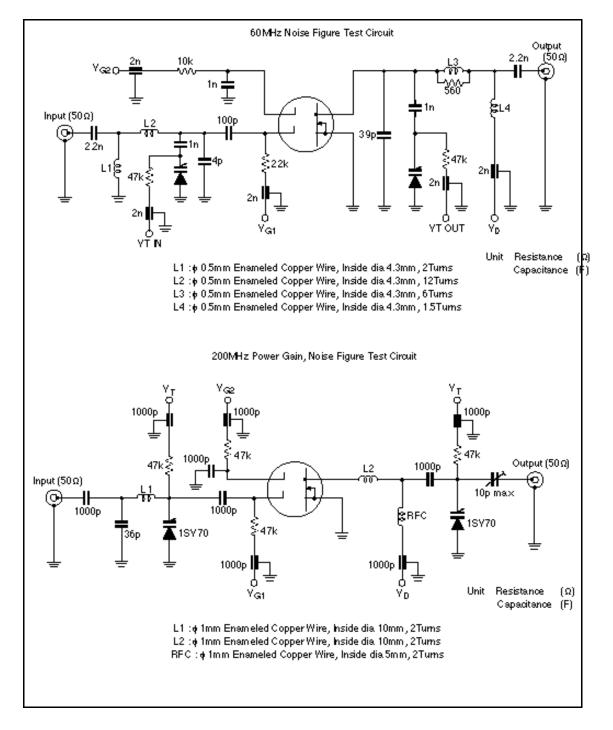
Attention: This device is very sensitive to electro static discharge. It is recommended to adopt appropriate cautions when handling this transistor.

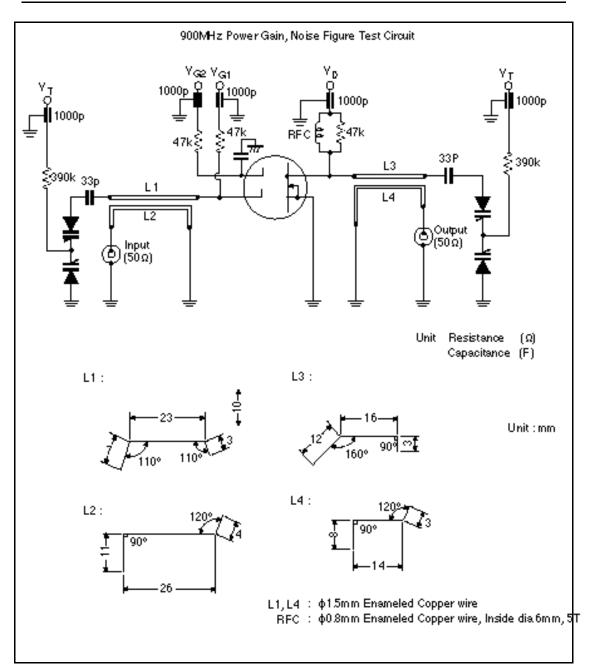
Electrical Characteristics (Ta = 25°C)

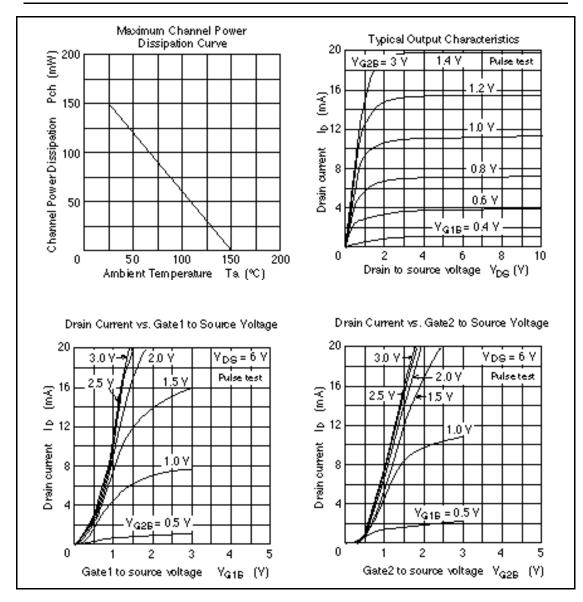
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(\text{BR})\text{DSX}}$	12	_	_	V	$I^{}_{\rm D}$ = 200 μA , $V^{}_{\rm G1S}$ = –3 V, $V^{}_{\rm G2S}$ = –3 V
Gate 1 to source breakdown voltage	$V_{(\text{BR})\text{G1SS}}$	±8	_	_	V	$I_{G1} = \pm 10 \ \mu A$, $V_{G2S} = V_{DS} = 0$
Gate 2 to source breakdown voltage	$V_{(BR)G2SS}$	±8	_	_	V	$I_{g_2} = \pm 10 \ \mu A$, $V_{g_{1S}} = V_{p_S} = 0$
Gate 1 cutoff current	I_{G1SS}	—	—	±100	nA	$V_{G1S} = \pm 6 V, V_{G2S} = V_{DS} = 0$
Gate 2 cutoff current	I _{G2SS}	—	_	±100	nA	$V_{G2S} = \pm 6 V$, $V_{G1S} = V_{DS} = 0$
Drain current	I _{DS(on)}	0.5	_	10	mA	$V_{\text{DS}} = 6 \text{ V}, V_{\text{G1S}} = 0.75 \text{ V}, V_{\text{G2S}} = 3 \text{ V}$
Gate 1 to source cutoff voltage	$V_{\text{G1S(off)}}$	0	_	+1.0	V	V_{DS} = 10 V, V_{G2S} = 3V, I_{D} = 100 µA
Gate 2 to source cutoff voltage	$V_{\text{G2S(off)}}$	0	-	+1.0	V	V_{DS} = 10 V, V_{G1S} = 3V, I_{D} = 100 µA
Forward transfer admittance	y _{fs}	16	20	_	mS	$V_{DS} = 6 V, V_{G2S} = 3V,$ $I_{D} = 10 mA, f = 1 kHz$
Input capacitance	Ciss	2.4	2.9	3.4	pF	$V_{DS} = 6 V, V_{G2S} = 3V,$ $I_{D} = 10 mA, f = 1 MHz$
Output capacitance	Coss	0.8	1.0	1.4	pF	
Reverse transfer capacitance	Crss	_	0.023	0.04	pF	
Power gain	PG	22	25	_	dB	$V_{DS} = 6 V, V_{G2S} = 3V,$ $I_{D} = 10 mA, f = 200 MHz$
Noise figure	NF	—	1.0	1.8	dB	-
Power gain	PG	12	15	_	dB	$V_{DS} = 6 V, V_{G2S} = 3V,$ $I_{D} = 10 mA, f = 900 MHz$
Noise figure	NF	—	3.2	4.5	dB	-
Noise figure	NF		2.8	3.5	dB	$V_{DS} = 6 V, V_{G2S} = 3V,$ $I_{D} = 10 mA, f = 60 MHz$

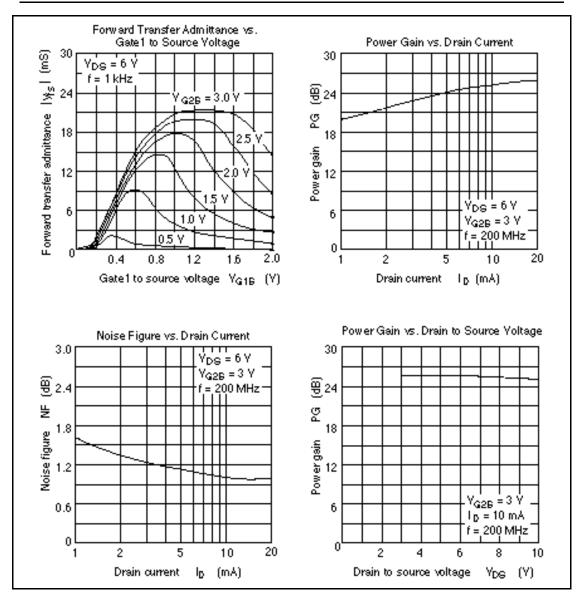
Note: Marking is "ZW-"

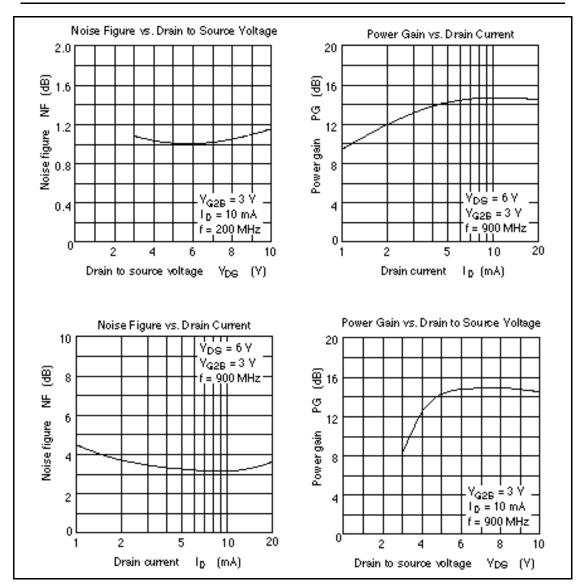
Main Characteristics

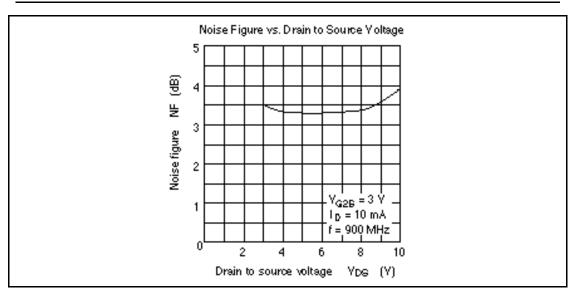


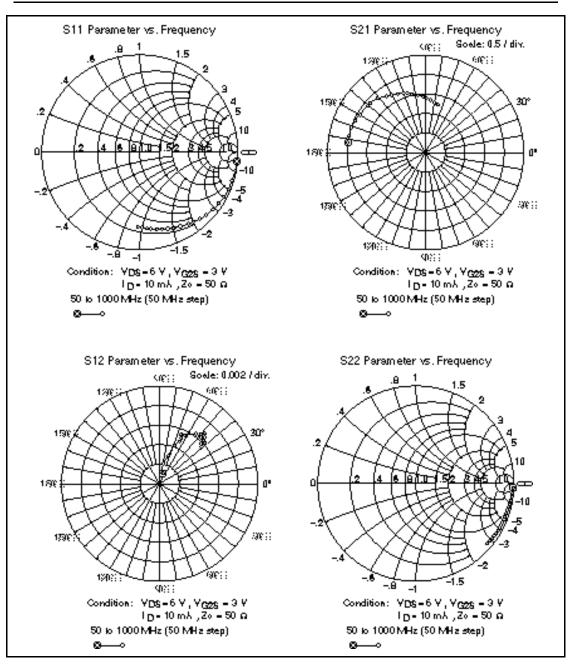












Freq.	S11		S21	S21		S12		S22	
(MHz)	MAG.	ANG.	MAG.	ANG.	MAG.	ANG.	MAG.	ANG.	
50	0.994	-5.8	2.04	173.6	0.00116	76.9	0.993	-2.2	
100	0.993	-11.0	2.02	167.4	0.00132	85.7	0.993	-4.5	
150	0.986	-16.8	2.00	161.5	0.00229	78.2	0.991	-6.4	
200	0.980	-22.5	1.98	155.5	0.00313	73.5	0.990	-8.5	
250	0.973	-27.8	1.94	149.6	0.00427	68.7	0.987	-10.5	
300	0.950	-33.0	1.90	142.6	0.00473	63.9	0.985	-12.5	
350	0.936	-38.3	1.86	137.1	0.00536	64.3	0.982	-14.4	
400	0.924	-43.4	1.83	131.6	0.00561	64.5	0.979	-16.2	
450	0.912	-48.0	1.77	126.8	0.00562	60.9	0.975	-18.2	
500	0.893	-52.5	1.71	121.0	0.00640	53.5	0.971	-20.2	
550	0.874	-57.3	1.67	115.5	0.00638	49.3	0.967	-22.0	
600	0.859	-62.0	1.64	111.1	0.00647	49.0	0.964	-23.9	
650	0.846	-66.1	1.58	106.7	0.00667	50.2	0.960	-25.8	
700	0.829	-69.8	1.50	102.1	0.00694	49.3	0.955	-27.6	
750	0.810	-74.2	1.46	97.1	0.00661	46.6	0.952	-29.4	
800	0.802	-78.0	1.44	92.7	0.00618	43.7	0.948	-31.2	
850	0.791	-81.6	1.38	88.9	0.00622	44.7	0.944	-33.2	
900	0.778	-84.6	1.34	84.2	0.00615	43.6	0.940	-35.1	
950	0.756	-88.5	1.30	80.2	0.00576	45.1	0.935	-36.8	
1000	0.751	-92.2	1.26	75.9	0.00562	40.7	0.932	-38.5	

S Parameter ($V_{DS} = 6 \text{ V}, V_{G2S} = 3 \text{ V}, I_D = 10 \text{ mA}, Z_O = 50$)

Cautions

- Hitachi neither warrants nor grants licenses of any rights of Hitachi's or any third party's patent, copyright, trademark, or other intellectual property rights for information contained in this document. Hitachi bears no responsibility for problems that may arise with third party's rights, including intellectual property rights, in connection with use of the information contained in this document.
- 2. Products and product specifications may be subject to change without notice. Confirm that you have received the latest product standards or specifications before final design, purchase or use.
- 3. Hitachi makes every attempt to ensure that its products are of high quality and reliability. However, contact Hitachi's sales office before using the product in an application that demands especially high quality and reliability or where its failure or malfunction may directly threaten human life or cause risk of bodily injury, such as aerospace, aeronautics, nuclear power, combustion control, transportation, traffic, safety equipment or medical equipment for life support.
- 4. Design your application so that the product is used within the ranges guaranteed by Hitachi particularly for maximum rating, operating supply voltage range, heat radiation characteristics, installation conditions and other characteristics. Hitachi bears no responsibility for failure or damage when used beyond the guaranteed ranges. Even within the guaranteed ranges, consider normally foreseeable failure rates or failure modes in semiconductor devices and employ systemic measures such as fail-safes, so that the equipment incorporating Hitachi product does not cause bodily injury, fire or other consequential damage due to operation of the Hitachi product.
- 5. This product is not designed to be radiation resistant.
- 6. No one is permitted to reproduce or duplicate, in any form, the whole or part of this document without written approval from Hitachi.
- Contact Hitachi's sales office for any questions regarding this document or Hitachi semiconductor products.

HITACHI

Semiconductor & IC Div. Nippon Bldg, 2-5-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109 URL North America : http:semiconductor.hitachi.com /

Burope Asia (Singapore) Asia (Taiwan) Asia (HongKong) Japan http://www.hitschi-eu.com/hel/ecg http://www.has.hitschi.com.sg/grp3/sicdlindex.htm http://www.hitschi.com.tw/B/Product/S/CD_Frame.htm http://www.hitschi.com.ht/engdbolgn_3/index.htm http://www.hitschi.com/p/Sicdlindex.htm

For further information write to: His dri Semicordustar (America) Inc. 2000 Sieme Point Perlawy Brietona CH, 94005 1807 Des 22 Feldlischen, Tel: c15 (200) 285-1801 Fiel: c

Bectronic components Group Domecher Straße 3 D35622 Feldlichen, Munich Germeny Tel: c40s (30) 9 9130-0 Rex: c40s (30) 9 29 30 00 Hischi Europe-Ltl. Bectronic Components Group.

Bectronic Componente Group. Whitebrock Perk Lower Cookhem Roed Meidenheed Berkehine SL6393, United Kingdom Tel: c446 (1523) 378422 Hischi Arie Pos Lel. 15 Colyer Gray 920-00 Hischi Tower Segepore 040218 Tel: 535-2100 Fex: 535-1533

Hinchi Arin Ltd. Turjesi Brunch Office 37, Hung Kuc Building, Na 167, Tun-Hvie North Roed, Tuipei (105) Tel: c885c (2) 2718-8985 Fux: c886c (2) 2718-8180 Hischi Aria (Hong Kong) Ltd. Group III (Bectronic Componente) 7.F., North Tower, World Finance Centre, Harbour Oby, Oniton Roed, Teim She Teui, Kowloon, Hong Kong Teil: 28250 (2) 735 522 18 Fax: 28250 [2] 735 0281 Tellec 40815 HITECHX

Copyright @Hitschi, Ltd., 1998. All right-reserved. Printed in Japan.